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Dated: December 20, 2005

Signature:

Linda J. Werk

Ref.: 7452-105/10313554
(PATENT)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Shih-Ping HSU

Confirmation No.: 6002

Application No.: 10/695,356

Group Art Unit: 2813

Filed: October 27, 2003

Examiner: Chen, Jack S J

For: SEMICONDUCTOR PACKAGE
SUBSTRATE HAVING CONTACT PAD
PROTECTIVE LAYER FORMED THEREON
AND METHOD FOR FABRICATING THE
SAME

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the requirement for restriction in the Office Action dated November 29, 2005, Applicant hereby elects with traverse, Species I (Figs. 3A-3I) drawn to a method for forming a semiconductor package substrate according to first embodiment..

REMARKS

Applicant elects Species I (Figs. 3A-3I), with traverse. An early action on the merits is awaited.